



100% Material Declaration Data Sheet PQ208

PK166 (v1.2.1) October 19, 2006

Material Declaration Data Sheet

Average Weight: 5.3 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.0689	1.30%
	Silicon	7440-21-3	100.00		0.0689	
Die Attach Material					0.03127	0.59%
	Silver	7440-22-4	78.00		0.0243906	
	Epoxy (EP)	Trade Secret	22.00		0.0068794	
Mold Compound					4.52726	85.42%
	Epoxy Resin (EP)	Trade Secret	9.00		0.4074534	
	Phenolic Resin	Trade Secret	7.00		0.3169082	
	Carbon Black	1333-86-4	0.50		0.0226363	
	Silica	60676-86-0	82.50		3.7349895	
	Bismuth	7440-69-9	Max 1.00		0.0452726	
Leadframe					0.62858	11.86%
	Copper	7440-50-8	98.85		0.62135133	
	Chromium	7440-47-3	0.30		0.00188574	
	Tin	7440-31-5	0.25		0.00157145	
	Zinc	7440-66-6	0.60		0.00377148	
Leadframe Plating					0.0053	0.10%
	Silver	7440-22-4	100.00		0.0053	
Bond Wire					0.00689	0.13%
	Gold	7440-57-5	100.00		0.00689	
Ext. Plating					0.0318	0.60%
	Tin	7440-31-5	85.00		0.02703	
	Lead	7439-92-1	15.00		0.00477	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
6/05/06	1.1	100% Material Declaration.
10/3/06	1.2	Updated component descriptions.
10/19/06	1.2.1	Editorial change; corrected typo in Substance Description.